

100V N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

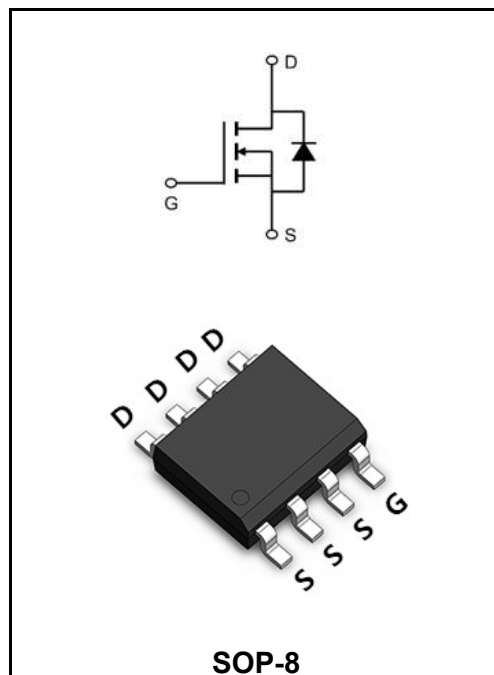
I_D	15A
V_{DSS}	100V
R_{DS(on)-typ}(@V_{GS}=10V)	<7.8mΩ(Typ:6.6 mΩ)

Description

- ◆Trench Power MV MOSFET technology
- ◆ Low R_{DS(ON)}
- ◆Low Gate Charge
- ◆Optimized for fast-switching applications

Applications

- ◆Synchronous Rectification in DC/DC and AC/DC Converters
- ◆Industrial and Motor Drive applications



Absolute Maximum Ratings T_A=25°C unless otherwise noted

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V _{DS}	100	V
Gate - Source Voltage	V _{GS}	±20	V
Drain Current, V _{GS} ⁷ @ 10V @T _A =25°C	I _D	15	A
Drain Current, V _{GS} ⁷ @ 10V @T _A =100°C	I _D	7.5	A
Pulsed Drain Current ³	I _{DM}	55	A
Avalanche energy L=0.3mH ³	E _{AS}	150	mJ
Total Power Dissipation ¹ @T _A =25°C	P _{Dsm}	3.1	W
Total Power Dissipation ¹ @T _A =70°C	P _{Dsm}	2.0	W
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	T _J	-55 to +150	°C
Maximum Thermal Resistance, Junction ambient	R _{θJA}	75	°C/W
Maximum Thermal Resistance, Junction-case	R _{θJC}	24	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	V(BR)DSS	100	107	-	V
Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V	I_{DSS}	-	-	1.0	μA
Gate to Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	I_{GSS}	-	-	±100	nA
Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	V_{GS(th)}	1.3	1.9	2.5	V
Static Drain-Source on-Resistance	V _{GS} =10V, I _D =7.5A	R_{DS(ON)}	-	6.6	7.8	mΩ
	V _{GS} =4.5V, I _D =7.5A		-	8.9	10.5	
Forward Transconductance	V _{DS} =5V, I _D =7.5A	g_{FS}	30	-	-	S
Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	R_g	-	2	-	Ω
Input Capacitance	V _{DS} =15V V _{GS} =0V f=1.0MHz	C_{iss}	-	2808	-	pF
Output Capacitance		C_{oss}	-	961	-	
Reverse Transfer Capacitance		C_{rss}	-	23	-	
Total Gate Charge(10V)	V _{DS} =50V V _{GS} =10V I _D =7.5A	Q_g	-	50	-	nC
Total Gate Charge(4.5V)		Q_g	-	33	-	
Gate-Source Charge		Q_{gs}	-	17	-	
Gate-Drain("Miller") Charge		Q_{gd}	-	11	-	
Turn-on delay time	V _{GS} =10V V _{DS} =50V R _L =2.5Ω R _{GEN} =3Ω	t_{d(on)}	-	15	-	ns
Turn-on Rise Time		T_r	-	12	-	
Turn-Off Delay Time		t_{d(OFF)}	-	25	-	
Turn-Off Fall Time		t_f	-	13	-	
Continuous Source Current ⁷		I_S	-	-	48	A
Diode Forward Voltage	V _{GS} =0V, I _S =1A	V_{SD}	-	0.7	0.95	V
Body Diode Reverse Recovery Time	I _F =15A, di/dt=500A/μs	trr		45		ns
Body Diode Reverse Recovery charge	I _F =15A, di/dt=500A/μs	Qrr		140		nC

Note :

1. The value of R_{θJA} is measured with the device mounted on 1in2 FR - 4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation PDSM is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
2. The power dissipation PD is based on T_{J(MAX)}=150°C, using junction - to - case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
3. Single pulse width limited by junction temperature T_{J(MAX)}=150°C.
4. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.
5. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
6. These curves are based on the junction - to - case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150°C. The SOA curve provides a single pulse rating.
7. The maximum current rating is package limited.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

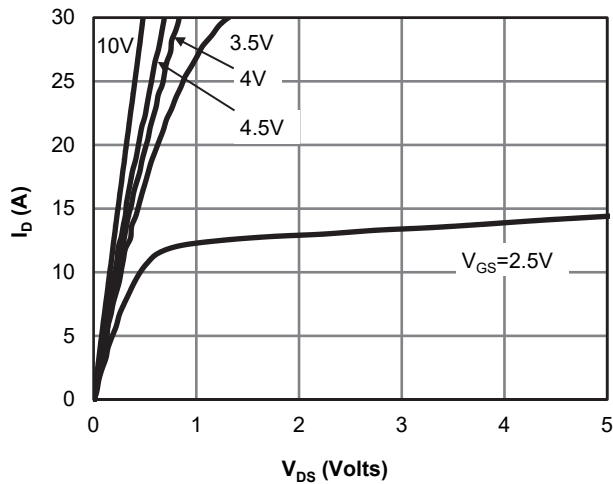


Fig 1: On-Region Characteristics

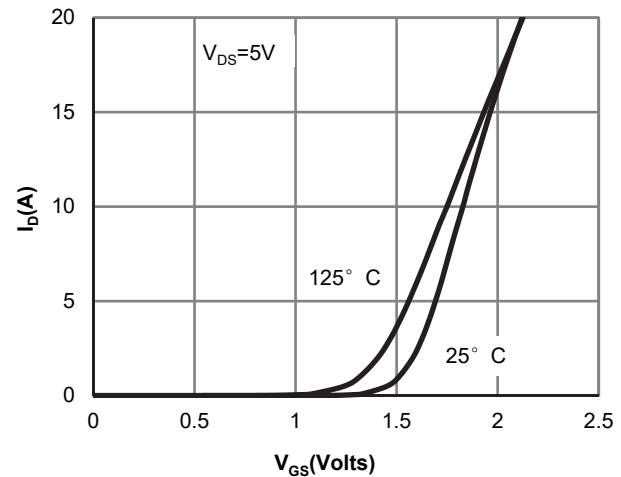


Figure 2: Transfer Characteristics

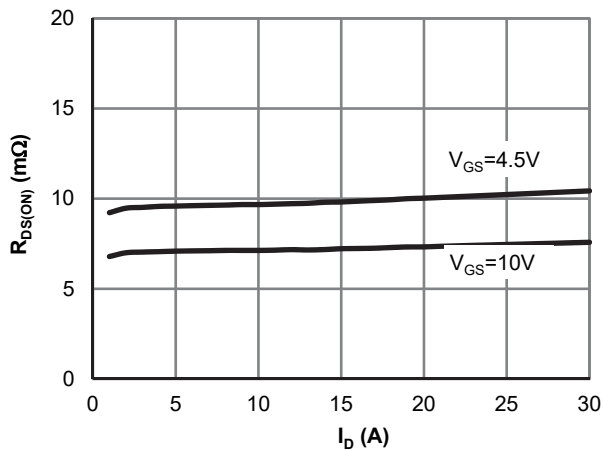


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

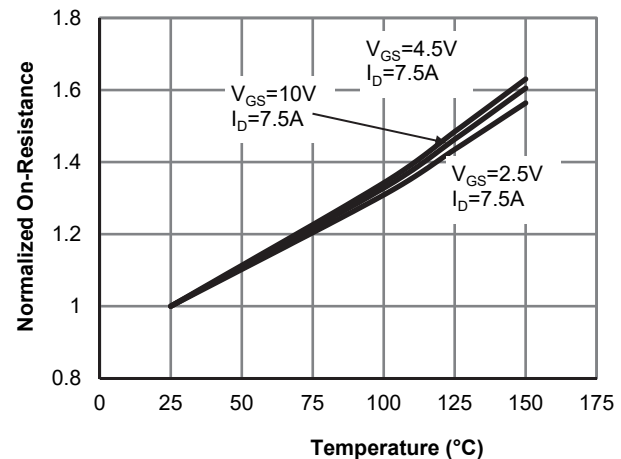


Figure 4: On-Resistance vs. Junction Temperature

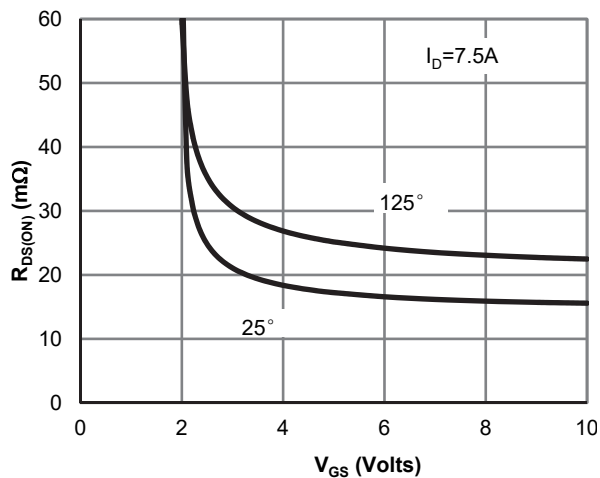


Figure 5: On-Resistance vs. Gate-Source Voltage

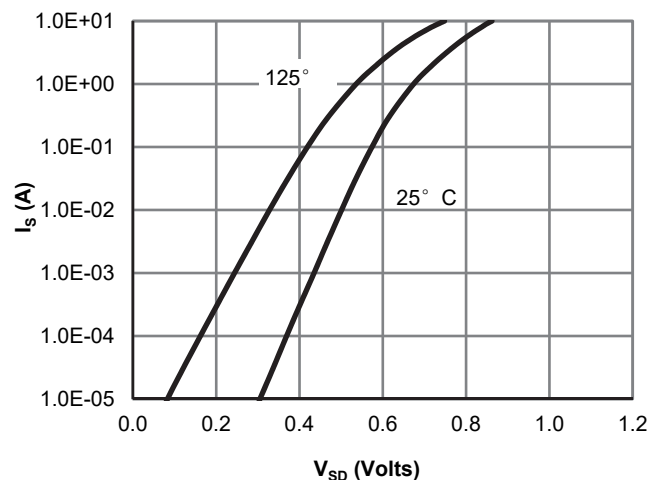


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

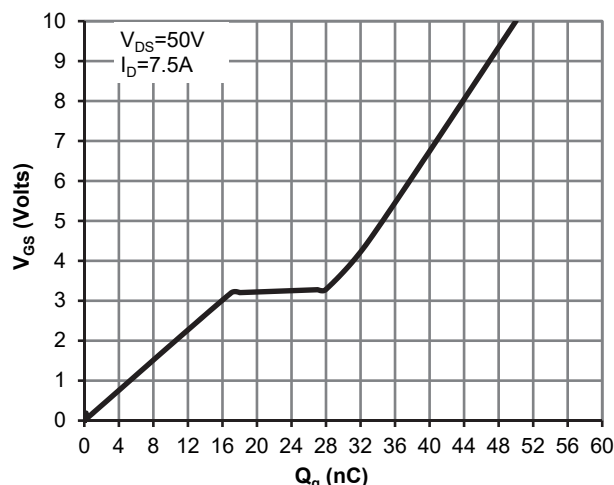


Figure 7: Gate-Charge Characteristics

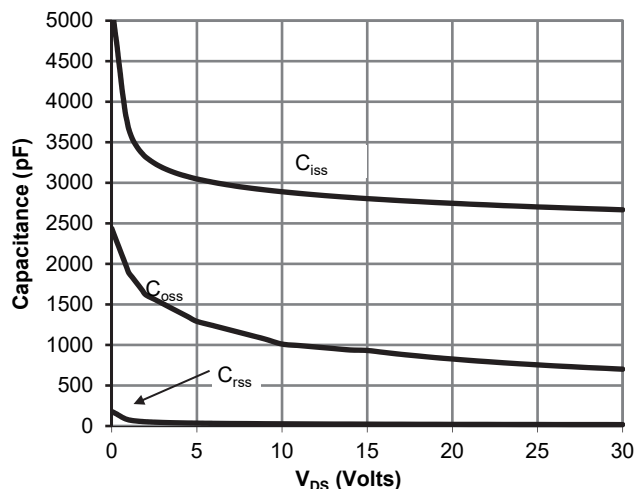


Figure 8: Capacitance Characteristics

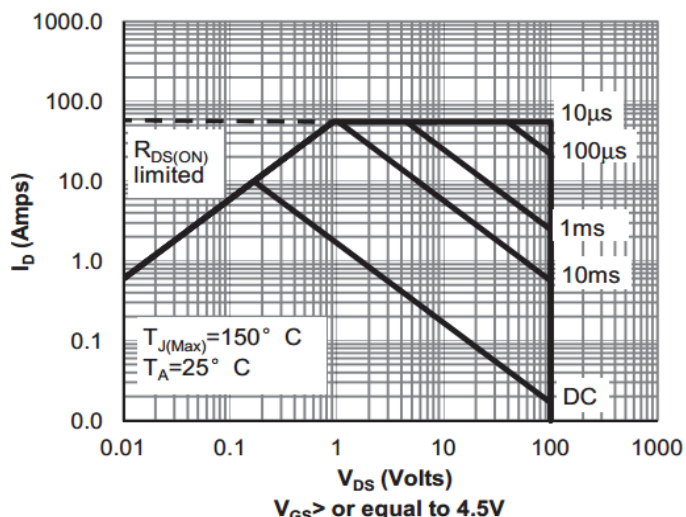


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

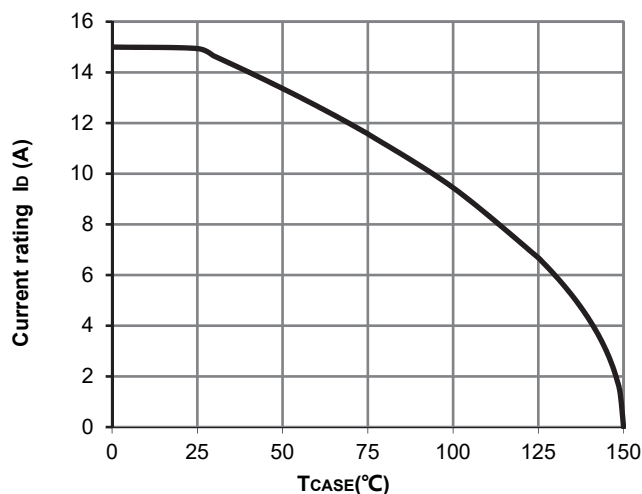


Figure 10: Current De-rating (Note F)

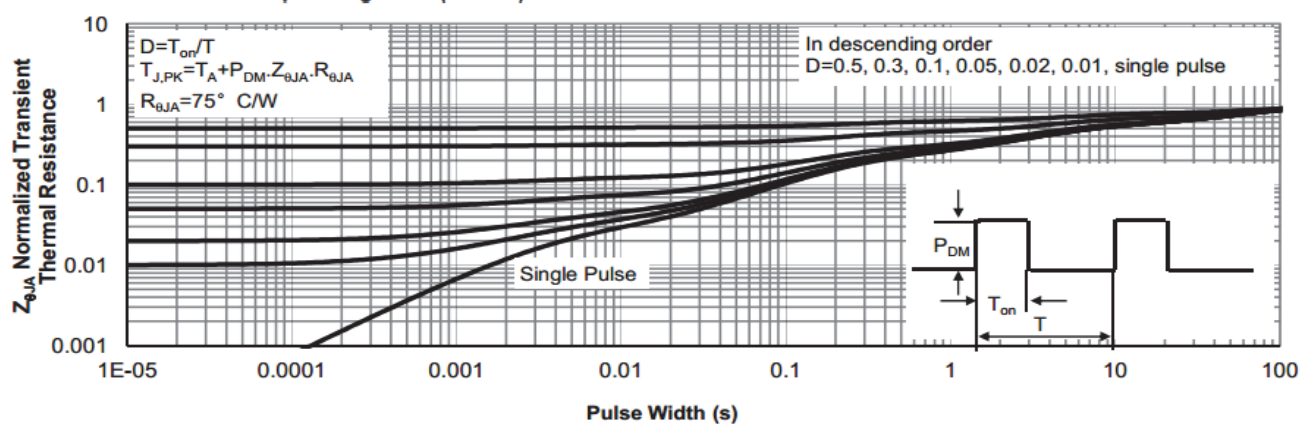


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Figure A: Gate Charge Test Circuit & Waveforms

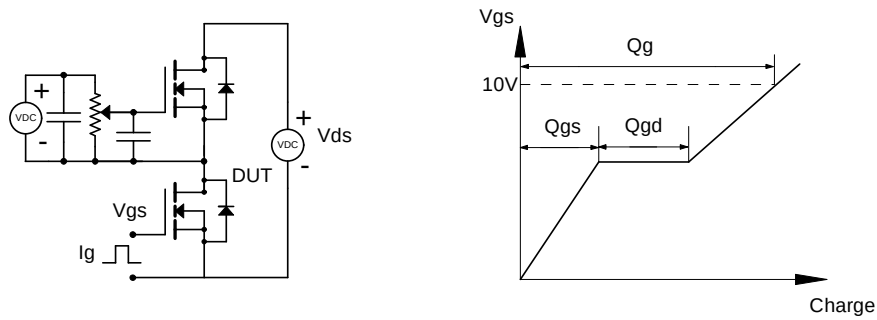


Figure B: Resistive Switching Test Circuit & Waveforms

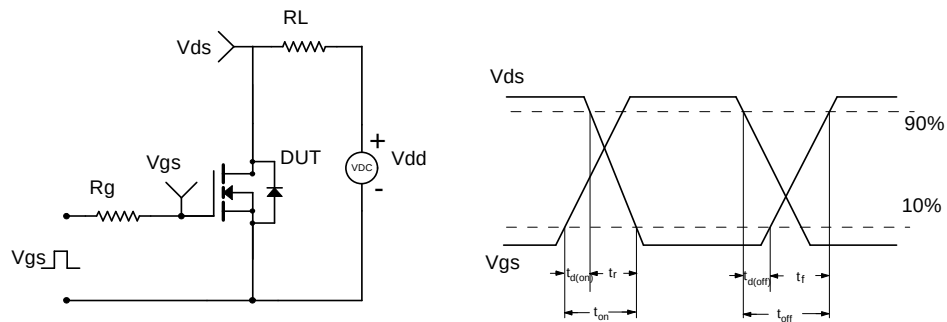


Figure C: Unclamped Inductive Switching (UIS) Test

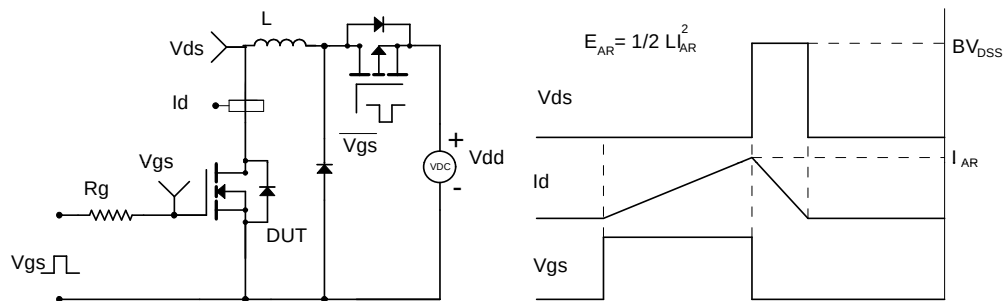
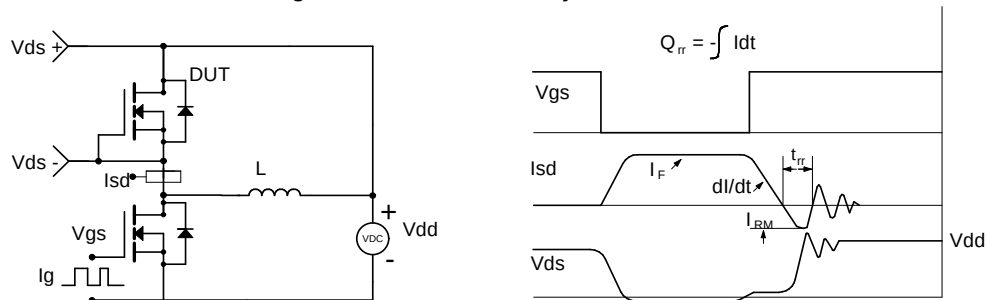
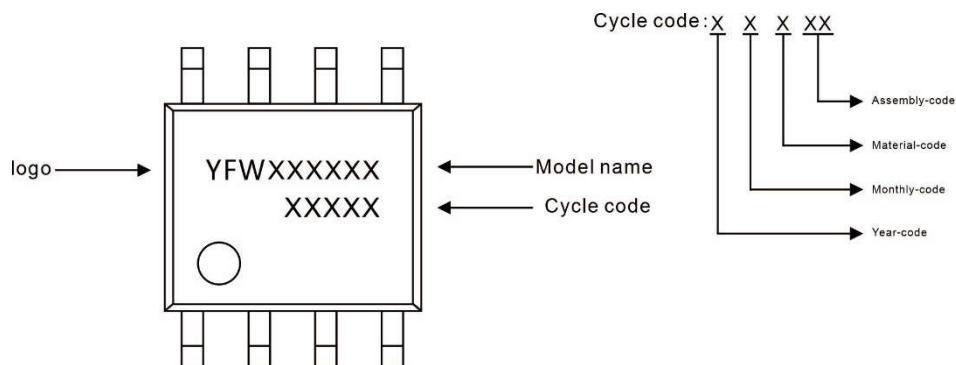


Figure D: Diode Recovery Test Circuit & Waveforms



Marking Diagram

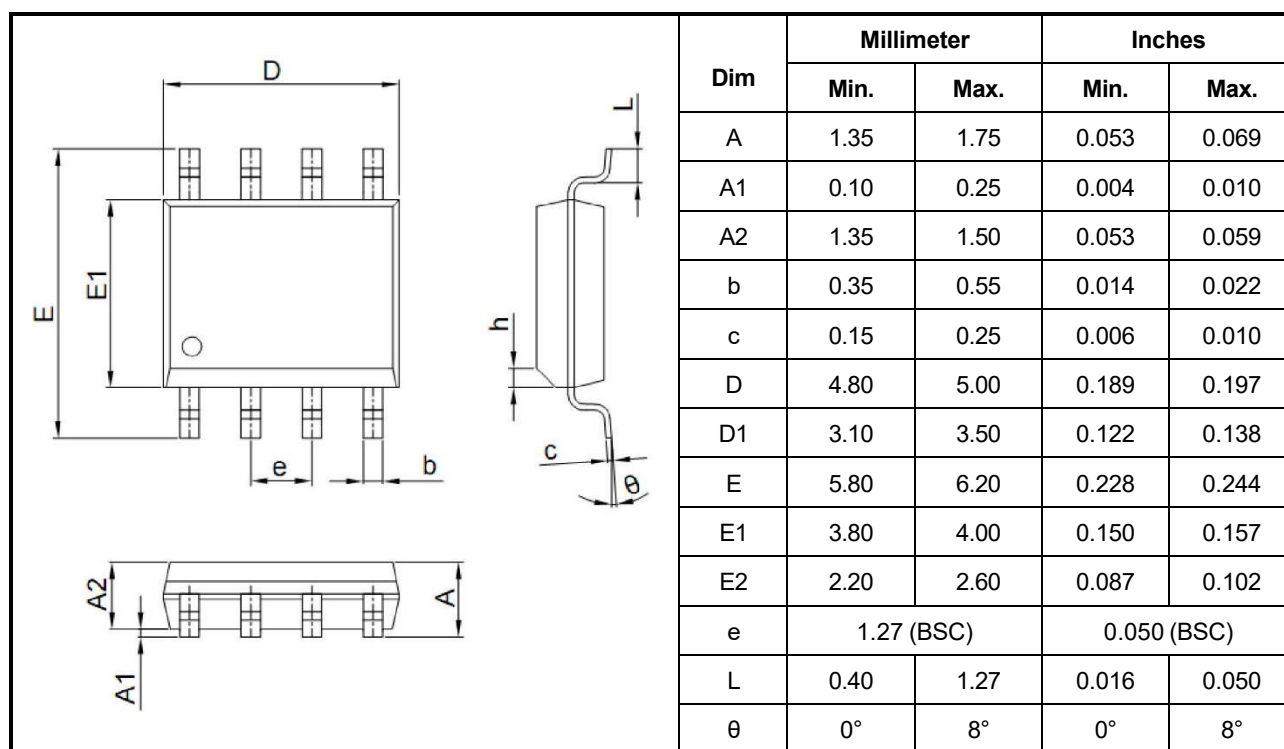


Ordering information

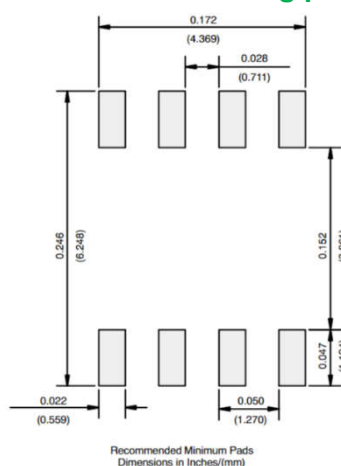
Package	Packing Description	Packing Quantity
SOP-8	Tape/Reel,13"reel	3000PCS/Reel 30000PCS/Carton

Package Dimensions

SOP-8



The recommended mounting pad size



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